FEATURES

- **Low Supply Voltage Range: 1.8 V to 3.6 V**
- **Ultralow-Power Consumption:**
  - **Active Mode: 160 µA at 1 MHz, 2.2 V**
  - **Standby Mode: 0.9 µA**
  - **Off Mode (RAM Retention) : 0.1 µA**
- **Contains Frequency-Hopping Firmware for Dolphin Reference Design**
- **Firmware Resides in ROM-Based Program Memory and is Fixed**
- **Simple UART Interface to an External Host/System Microcontroller**
- **Pre-Defined Protocol for Communication with an External Host/System Microcontroller**
- **Five Power-Saving Modes**
- **Wake-Up From Standby Mode in less than 6 µs**
- **16-Bit RISC Architecture, 125-ns Instruction Cycle Time**
- **Serial Communication Interface (USART), Software Selects Asynchronous UART or Synchronous SPI**
- **Available in 64-Pin Quad Flat Pack (QFP)**
- **For Complete Dolphin Product Description, See the *Dolphin Frequency Hopping Spread Spectrum Evaluation Kit Hardware and Software User's Guide* (SLLU090)**

DESCRIPTION

The DBB03 is a baseband ASIC for the "Dolphin" reference design. The firmware for the Dolphin reference design resides in the ROM-based program memory of the DBB03, and thus can be readily interfaced with a TRF6903 single-chip RF Transceiver to generate a frequency hopping wireless UART "Dolphin" reference design chipset. This is illustrated in Figure 1.

The DBB03 baseband ASIC in addition to being a RF baseband processor is also responsible for communications with an external host/system micrcontroller. In a typical end user application, the Dolphin chipset will be connected up to an external host/system microcontroller that will send configuration messages, RF transmission messages into the Dolphin chipset, or receive status, RF messages received from the Dolphin chipset.

Any catalog low-cost host/system microcontroller can be interfaced to the Dolphin chipset as long as the Dolphin host interface protocol for communication is adhered to. (See Application Note Dolphin - Frequency Hopping Spread Spectrum Chipset Host Interface Protocol TI Literature SWRA043) Texas Instruments recommends its ultra-low power MSP430 series of microcontrollers to interface with Dolphin.

The interface between the DBB03 baseband ASIC and an external host/system microcontroller is a simple UART consisting of RX and TX data lines. (See Application Note *Interfacing Dolphin to an External System Microcontroller*, TI Literature SWRA045).

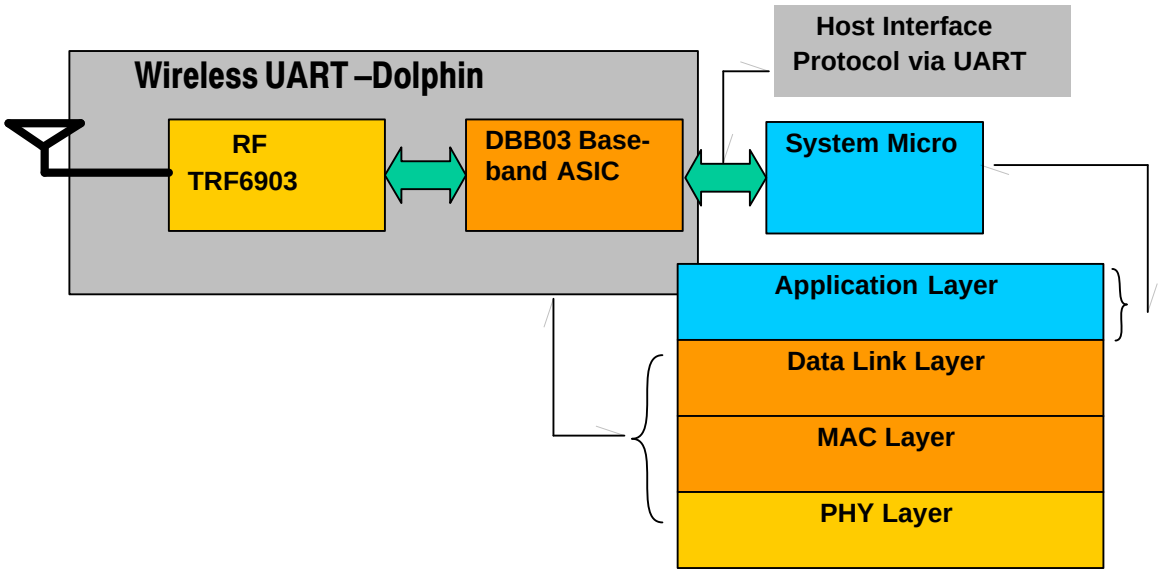


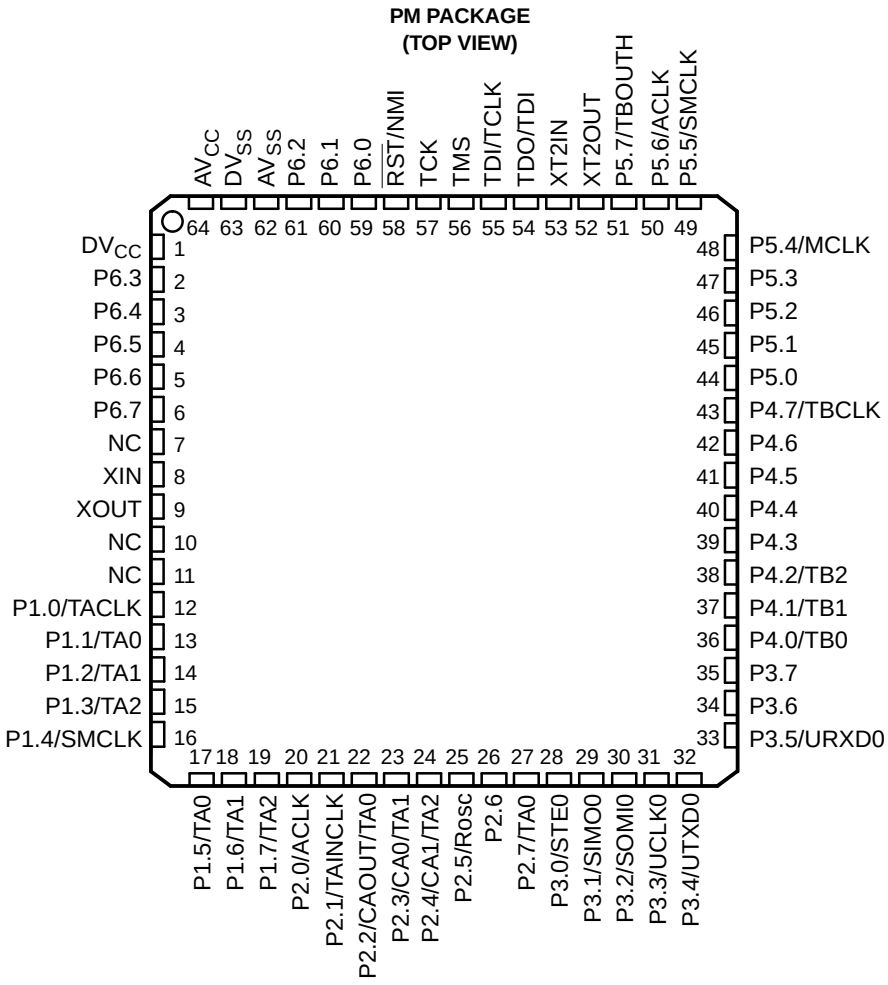
Figure 1. DBB03 - Baseband ASIC for the Dolphin Chipset

The Wireless UART Dolphin chipset is a true Data-In/RF-out and RF-in/Data-out solution with all aspects of data management and frequency hopping implemented in firmware residing on the DBB03. As illustrated in Figure 1, the DBB03 baseband ASIC contains the complete firmware for Dolphin (PHYsical, MAC and the Data Link layer), while the application layer protocol is handled by the external Host/System Microcontroller.

AVAILABLE OPTIONS

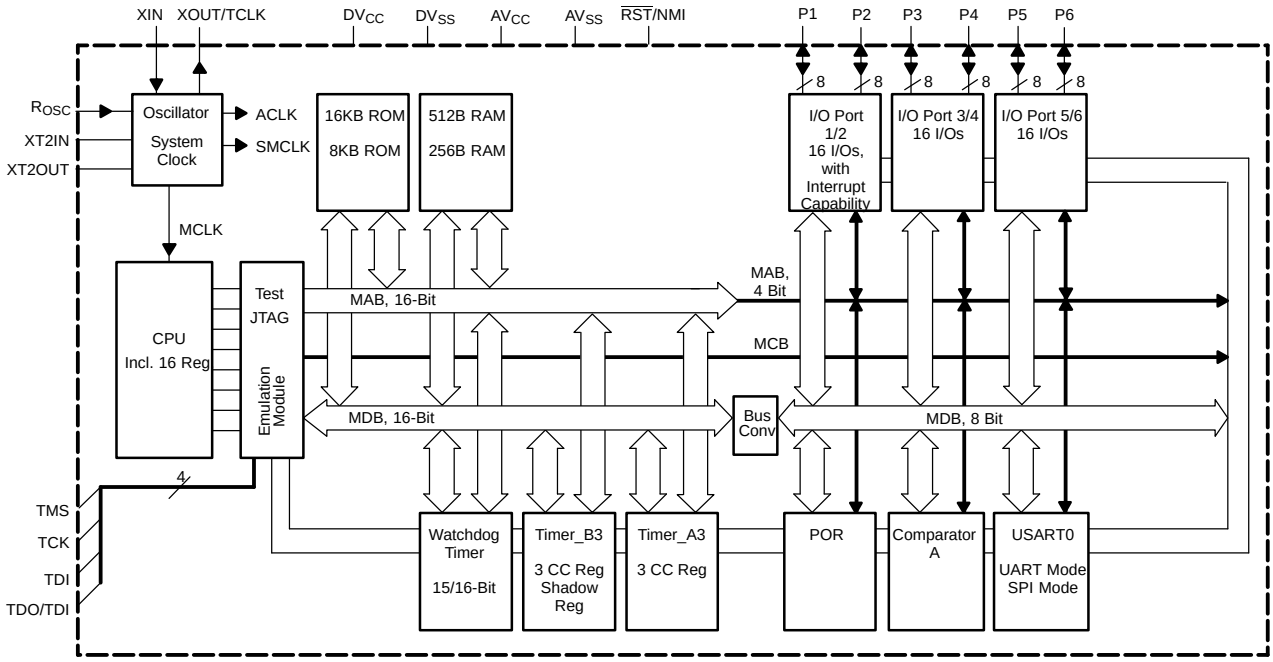
T_A	PACKAGE	ORDER NUMBER
-40°C to 85°C	Plastic 64-pin QFP (PM)	DBB03 IPM

PIN DESIGNATION, DBB03 Baseband ASIC



NC − No internal connection

FUNCTIONAL BLOCK DIAGRAMS: DBB03



DEVICE INFORMATION

TERMINAL FUNCTIONS

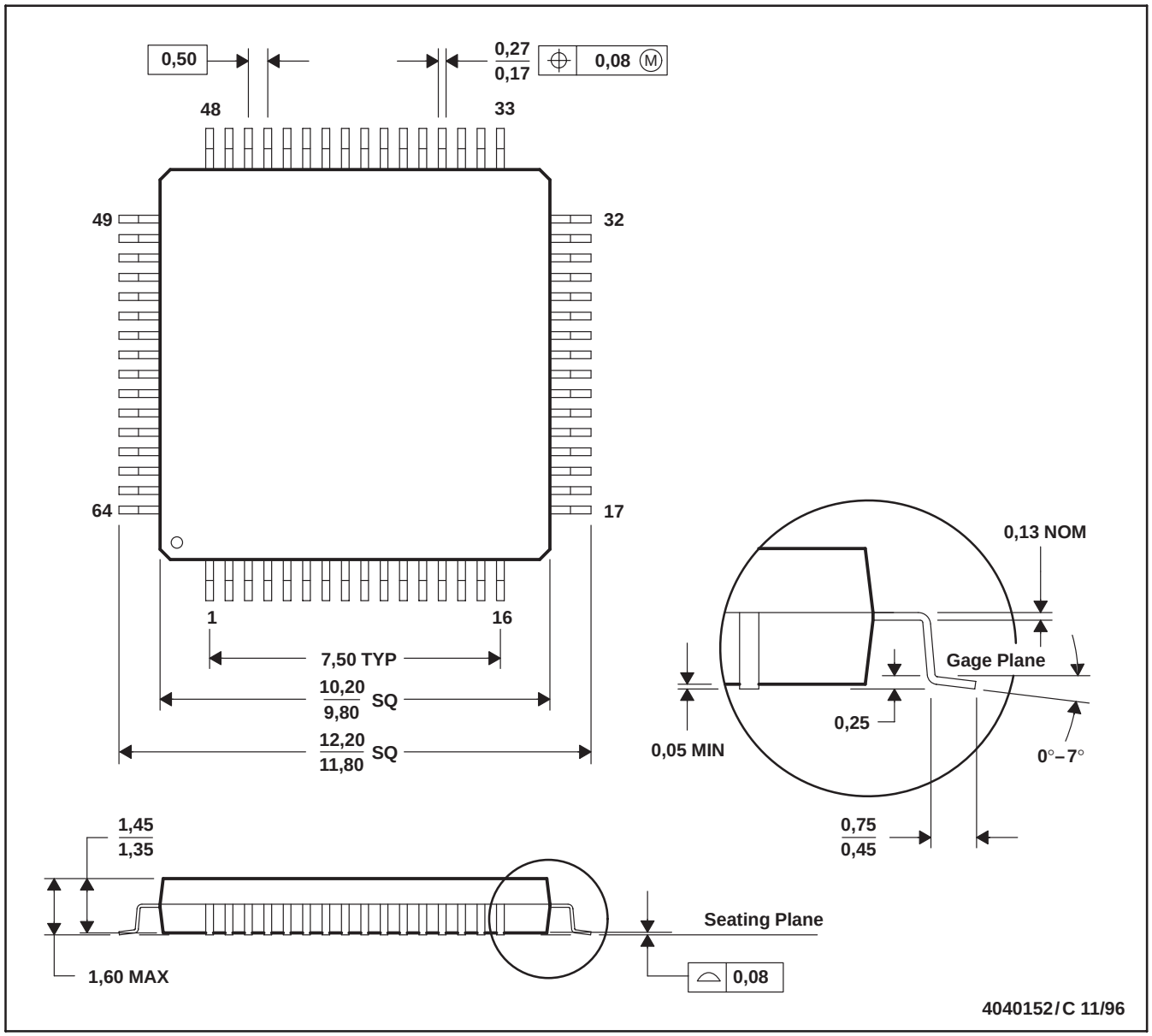
TERMINAL		I/O	DESCRIPTION
NAME	NO.		
AV_{CC}	64		Supply voltage, positive terminal. AV_{CC} and DV_{CC} are internally connected together.
AV_{SS}	64		Supply voltage, negative terminal. AV_{SS} and DV_{SS} are internally connected together.
DV_{CC}	1		Supply voltage, positive terminal. AV_{CC} and DV_{CC} are internally connected together.
DV_{SS}	63		Supply voltage, negative terminal. AV_{SS} and DV_{SS} are internally connected together.
P1.0/TACLK	12	I/O	General-purpose digital I/O pin/Timer_A, clock signal TACLK input
P1.1/TA0	13	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI0A input, compare: Out0 output
P1.2/TA1	14	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI1A input, compare: Out1 output
P1.3/TA2	15	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI2A input, compare: Out2 output
P1.4/SMCLK	16	I/O	General-purpose digital I/O pin/SMCLK signal output
P1.5/TA0	17	I/O	General-purpose digital I/O pin/Timer_A, compare: Out0 output
P1.6/TA1	18	I/O	General-purpose digital I/O pin/Timer_A, compare: Out1 output
P1.7/TA2	19	I/O	General-purpose digital I/O pin/Timer_A, compare: Out2 output
P2.0/ACLK	20	I/O	General-purpose digital I/O pin/ACLK output
P2.1/TAINCLK	21	I/O	General-purpose digital I/O pin/Timer_A, clock signal at INCLK
P2.2/CAOUT/TA0	22	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI0B input/Comparator_A output
P2.3/CA0/TA1	23	I/O	General-purpose digital I/O pin/Timer_A, compare: Out1 output/Comparator_A input
P2.4/CA1/TA2	24	I/O	General-purpose digital I/O pin/Timer_A, compare: Out2 output/Comparator_A input
P2.5/R_{OSC}	25	I/O	General-purpose digital I/O pin/input for external resistor defining the DCO nominal frequency
P2.6	26	I/O	General-purpose digital I/O pin

DEVICE INFORMATION (continued)

TERMINAL FUNCTIONS (continued)

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
P2.7/TA0	27	I/O	General-purpose digital I/O pin/Timer_A, compare: Out0 output
P3.0/STE0	28	I/O	General-purpose digital I/O pin/slave transmit enable - USART0/SPI mode
P3.1/SIMO0	29	I/O	General-purpose digital I/O pin/slave in/master out of USART0/SPI mode
P3.2/SOMI0	30	I/O	General-purpose digital I/O pin/slave out/master in of USART0/SPI mode
P3.3/UCLK0	31	I/O	General-purpose digital I/O pin/external clock input - USART0/UART or SPI mode, clock output - USART0/SPI mode
P3.4/UTXD0	32	I/O	General-purpose digital I/O pin/transmit data out - USART0/UART mode
P3.5/URXD0	33	I/O	General-purpose digital I/O pin/receive data in - USART0/UART mode
P3.6	34	I/O	General-purpose digital I/O pin
P3.7	35	I/O	General-purpose digital I/O pin
P4.0/TB0	36	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI0A/B input, compare: Out0 output
P4.1/TB1	37	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI1A/B input, compare: Out1 output
P4.2/TB2	38	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI2A/B input, compare: Out2 output
P4.3	39	I/O	General-purpose digital I/O pin
P4.4	40	I/O	General-purpose digital I/O pin
P4.5	41	I/O	General-purpose digital I/O pin
P4.6	42	I/O	General-purpose digital I/O pin
P4.7/TBCLK	43	I/O	General-purpose digital I/O pin/Timer_B, clock signal TBCLK input
P5.0	44	I/O	General-purpose digital I/O pin
P5.1	45	I/O	General-purpose digital I/O pin
P5.2	46	I/O	General-purpose digital I/O pin
P5.3	47	I/O	General-purpose digital I/O pin
P5.4/MCLK	48	I/O	General-purpose digital I/O pin/main system clock MCLK output
P5.5/SMCLK	49	I/O	General-purpose digital I/O pin/submain system clock SMCLK output
P5.6/ACLK	50	I/O	General-purpose digital I/O pin/auxiliary clock ACLK output
P5.7/TBOUTH	51	I/O	General-purpose digital I/O pin/switch all PWM digital output ports to high impedance - Timer_B7 TB0 to TB2
P6.0	59	I/O	General-purpose digital I/O pin
P6.1	60	I/O	General-purpose digital I/O pin
P6.2	61	I/O	General-purpose digital I/O pin
P6.3	2	I/O	General-purpose digital I/O pin
P6.4	3	I/O	General-purpose digital I/O pin
P6.5	4	I/O	General-purpose digital I/O pin
P6.6	5	I/O	General-purpose digital I/O pin
P6.7	6	I/O	General-purpose digital I/O pin
$\overline{\text{RST}}$/NMI	58	I	Reset input, nonmaskable interrupt input port
TCK	57	I	Test clock. TCK is the clock input port for device programming test.
TDI/TCLK	55	I	Test data input or test clock input. TDI is used as a data input port. The device protection fuse is connected to TDI.
TDO/TDI	54	I/O	Test data output port. TDO/TDI data output
TMS	56	I	Test mode select. TMS is used as an input port for device test.
NC	7, 10, 11		No internal connection
XIN	8	I	Input port for crystal oscillator XT1. Standard or watch crystals can be connected.
XOUT	9	O	Output terminal of crystal oscillator XT1
XT2IN	53	I	Input port for crystal oscillator XT2. Only standard crystals can be connected.
XT2OUT	52	O	Output terminal of crystal oscillator XT2

PM (S-PQFP-G64) **PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-026
D. May also be thermally enhanced plastic with leads connected to the die pads.

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